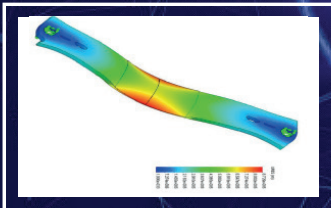
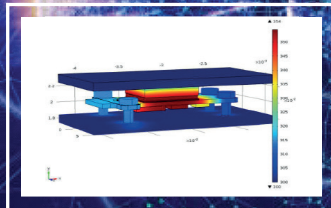
ALTER

PACKAGING & ASSEMBLY SERVICES

- **Sub-contract design and assembly for optoelectronics and microelectronic devices**
  - » Small batch prototypes through to volume manufacturing

- **Design Services**
  - » Optical, mechanical & thermal modelling
  - » Advanced electro / optical package design
  - » Design for manufacture

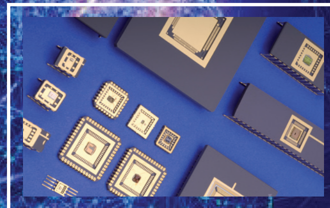


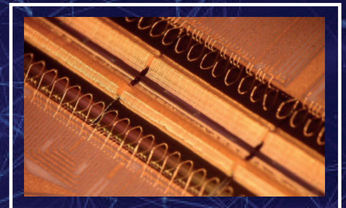


- **MIL-STD-883 and ESCC Standards**

  Focussed areas of excellence
  - » Wafer processing
  - » Precision placement and auto die attach
  - » Wire Bond – Au & Al, ball & wedge
  - » Hermetic sealing
  - » Optical alignment
  - » Laser packaging
  - » Photonic IC packaging

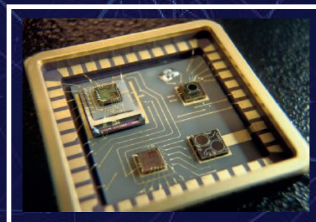
- **Experienced end-to-end Manufacturer: wafer processing though to finished packaged product**
  - » ISO7 Clean Room assembly
  - » Optoelectronic & Optical Packaging
  - » Microelectronic & MEMS Packaging
  - » Electrical and optical test

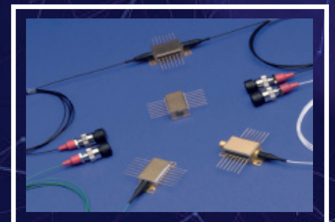




- » QC & Inspection
- » Die shear and wire strength tests
- » Real-time X-RAY
- » Placement accuracy measurements

- » Working with our parent Alter Technology to provide fully tested & qualified product solutions
- » EEE procurement, Test, Screening & Qualification





www.altertechnology-group.com